

# MURHD560T4, MURHD560W1T4

## MEGAHERTZ™ Power Rectifier

### Features and Benefits

- Ultrafast 30 Nanosecond Recovery Times
- 175°C Operating Junction Temperature
- High Temperature Glass Passivated Junction
- High Voltage Capability to 600 Volts
- These are Pb-Free Devices

### Applications

- Power Supplies
- Inverters
- Free Wheeling Diodes

### Mechanical Characteristics

- Case: Epoxy, Molded
- Epoxy Meets UL 94 V-0 @ 0.125 in
- Weight: 0.4 g (approximately)
- Finish: All External Surfaces Corrosion Resistant and Terminal Leads are Readily Solderable
- Lead Temperature for Soldering Purposes:  
260°C Max. for 10 Seconds
- ESD Ratings: Machine Model = C (>400 V)  
Human Body Model = 3B (>8000 V)

### MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	$V_{RRM}$ $V_{RWM}$ $V_R$	600	V
Average Rectified Forward Current (Rated $V_R$ , $T_C = 159^\circ\text{C}$ )	$I_{F(AV)}$	5.0	A
Non-Repetitive Peak Surge Current (Surge Applied at Rated Load Conditions Halfwave, Single Phase, 60 Hz)	$I_{FSM}$	50	A
Operating Junction and Storage Temperature Range	$T_J, T_{stg}$	-65 to +175	°C

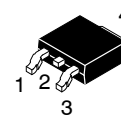
Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.



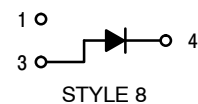
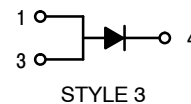
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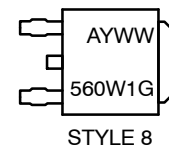
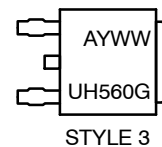
**ULTRAFAST RECTIFIER  
5.0 AMPERES  
600 VOLTS**



**DPAK  
CASE 369C  
STYLES 3, 8**



### MARKING DIAGRAMS



UH560 = MURHD560T4  
560W1 = MURHD560W1T4  
A = Assembly Location  
Y = Year  
WW = Work Week  
G = Pb-Free Package

### ORDERING INFORMATION

Device	Package	Shipping†
MURHD560T4G	DPAK (Pb-Free)	2500 / Tape & Reel
MURHD560W1T4G	DPAK (Pb-Free)	2500 / Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.

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## THERMAL CHARACTERISTICS

Rating	Symbol	Value	Unit
Maximum Thermal Resistance, Junction to Case	$R_{\theta JC}$	2.5	$^{\circ}C/W$
Maximum Thermal Resistance, Junction to Ambient (Note 1)	$R_{\theta JA}$	49.5	$^{\circ}C/W$

## ELECTRICAL CHARACTERISTICS

Rating	Symbol	Value	Unit
Maximum Instantaneous Forward Voltage (Note 2) ( $I_F = 5.0$ Amps, $T_C = 25^{\circ}C$ ) ( $I_F = 5.0$ Amps, $T_C = 125^{\circ}C$ )	$V_F$	2.7 1.65	V
Maximum Instantaneous Reverse Current (Note 2) (Rated dc Voltage, $T_C = 25^{\circ}C$ ) (Rated dc Voltage, $T_C = 125^{\circ}C$ )	$I_R$	10 70	$\mu A$
Maximum Reverse Recovery Time ( $I_F = 1.0$ Amp, $di/dt = 50$ Amps/ $\mu s$ , $V_R = 30$ V, $T_J = 25^{\circ}C$ )	$t_{rr}$	30	ns

1. Rating applies when surface mounted on a 1.5 mm FR4 PC board with a 1 oz. thick, 700 mm<sup>2</sup> Cu area.
2. Pulse Test: Pulse Width = 300  $\mu s$ , Duty Cycle  $\leq 2.0\%$ .

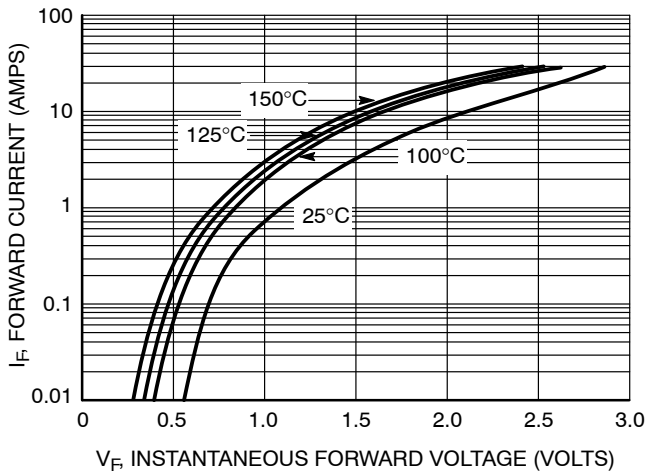


Figure 1. Typical Forward Voltage

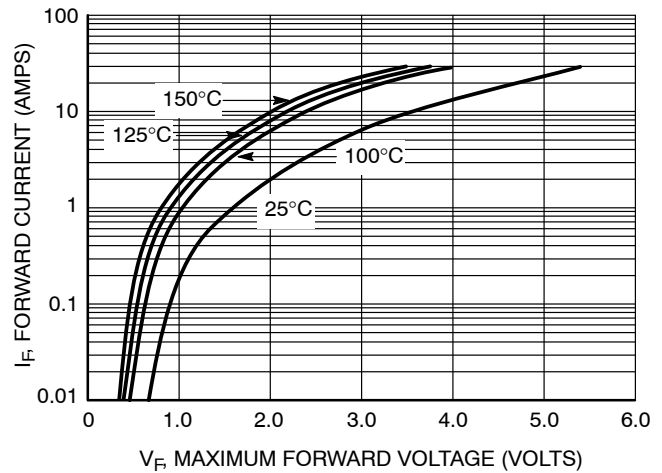


Figure 2. Maximum Forward Voltage

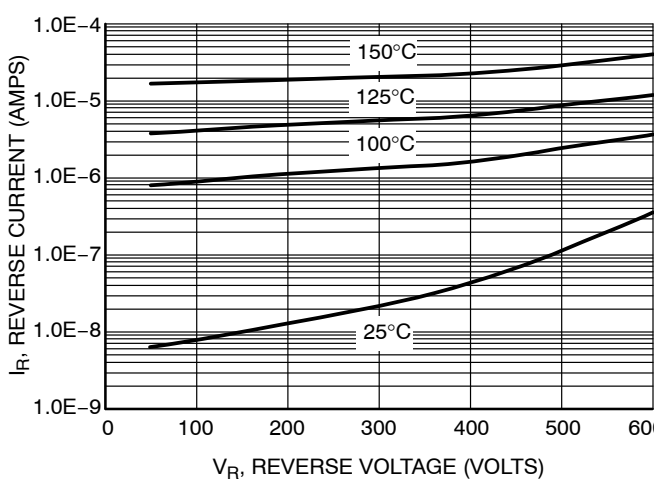


Figure 3. Typical Reverse Current

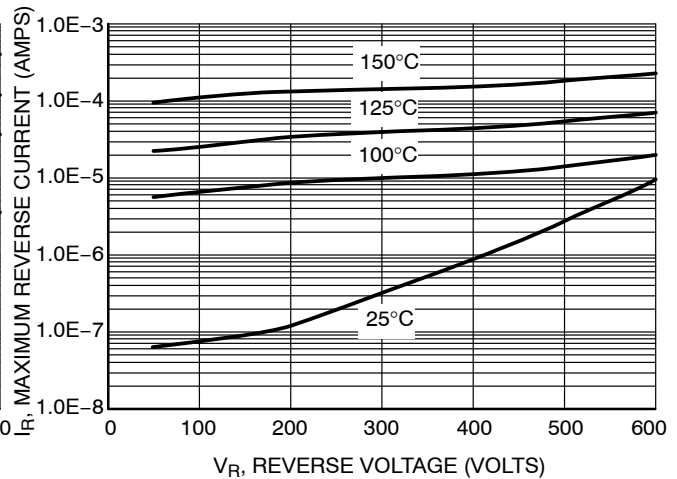


Figure 4. Maximum Reverse Current

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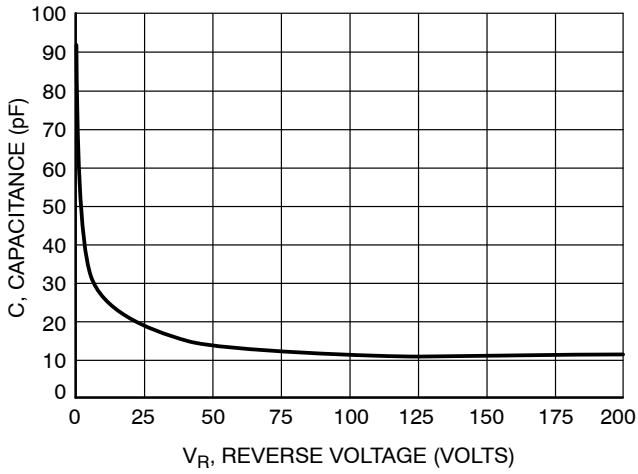


Figure 5. Typical Capacitance

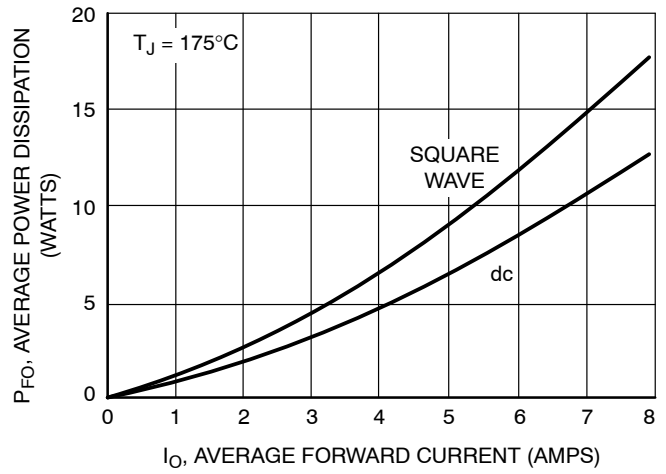


Figure 6. Forward Power Dissipation

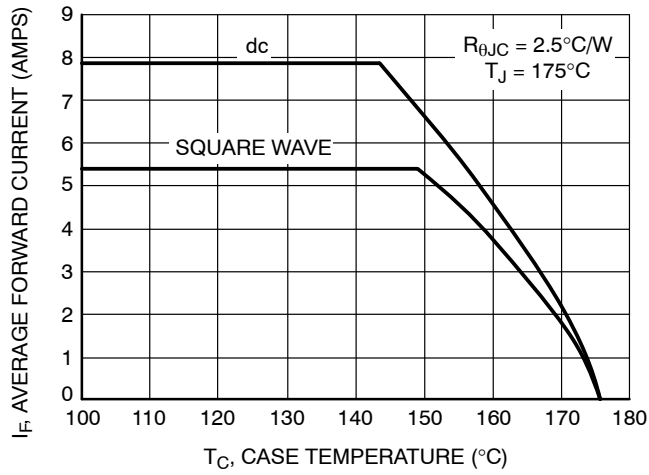


Figure 7. Current Derating

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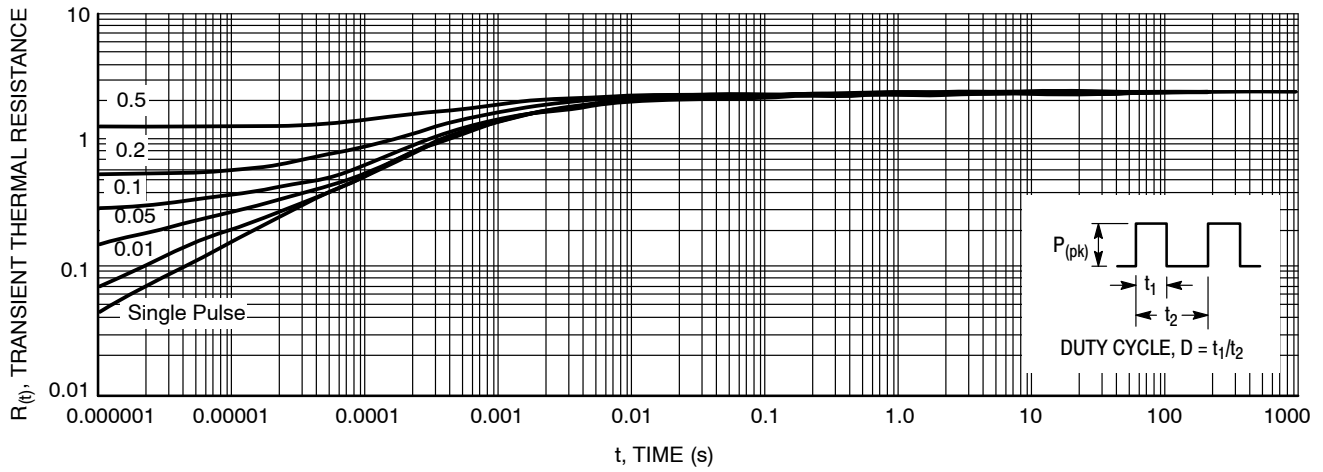


Figure 8. Thermal Response, Junction to Case

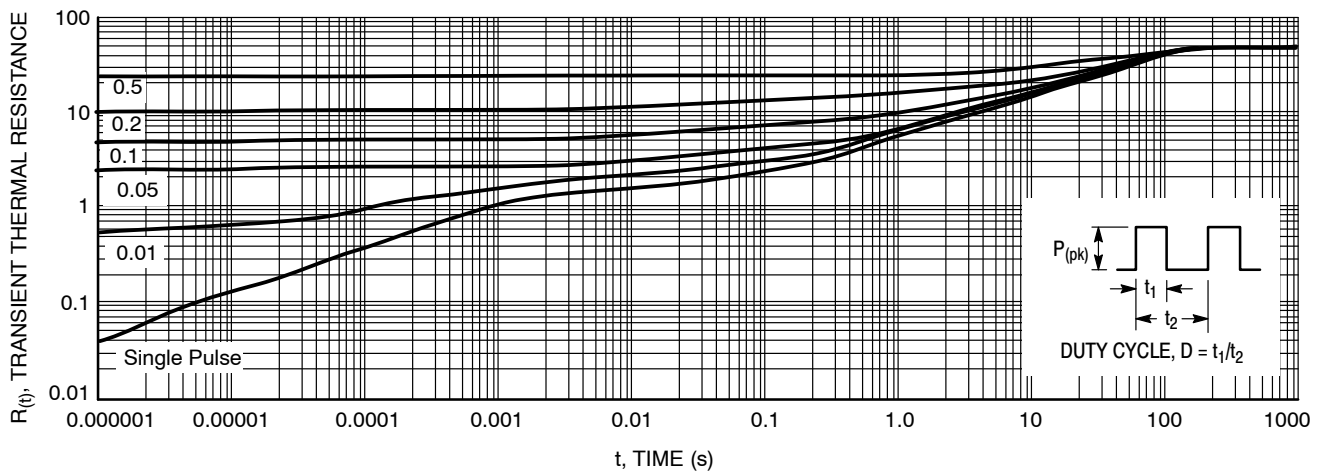
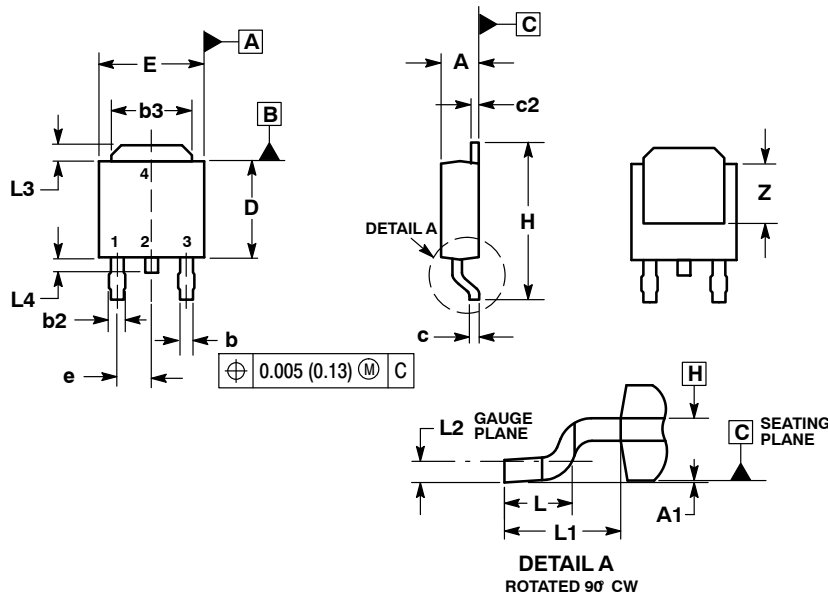


Figure 9. Thermal Response, Junction to Ambient

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## PACKAGE DIMENSIONS

### DPAK (SINGLE GAUGE) CASE 369C-01 ISSUE D

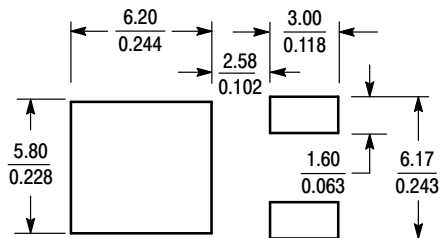


#### NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: INCHES.
3. THERMAL PAD CONTOUR OPTIONAL WITHIN DIMENSIONS b3, L3 and Z.
4. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR BURRS. MOLD FLASH, PROTRUSIONS, OR GATE BURRS SHALL NOT EXCEED 0.006 INCHES PER SIDE.
5. DIMENSIONS D AND E ARE DETERMINED AT THE OUTERMOST EXTREMES OF THE PLASTIC BODY.
6. DATUMS A AND B ARE DETERMINED AT DATUM PLANE H.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.086	0.094	2.18	2.38
A1	0.000	0.005	0.00	0.13
b	0.025	0.035	0.63	0.89
b2	0.030	0.045	0.76	1.14
b3	0.180	0.215	4.57	5.46
c	0.018	0.024	0.46	0.61
c2	0.018	0.024	0.46	0.61
D	0.235	0.245	5.97	6.22
E	0.250	0.265	6.35	6.73
e	0.090 BSC		2.29 BSC	
H	0.370	0.410	9.40	10.41
L	0.055	0.070	1.40	1.78
L1	0.108 REF		2.74 REF	
L2	0.020 BSC		0.51 BSC	
L3	0.035	0.050	0.89	1.27
L4	---	0.040	---	1.01
Z	0.155	---	3.93	---

### SOLDERING FOOTPRINT\*



SCALE 3:1 (mm/inches)

#### STYLE 3:

- PIN 1. ANODE
- CATHODE
- ANODE
- CATHODE

#### STYLE 8:

- PIN 1. N/C
- CATHODE
- ANODE
- CATHODE

\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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